

## Dual N-Channel 20V(D-S) MOSFET

Product summary		
$V_{DS}$	20	V
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) Typ.	22	mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$ ) Typ.	30	mΩ
$I_D(T_C=25^{\circ}C)$	5	A

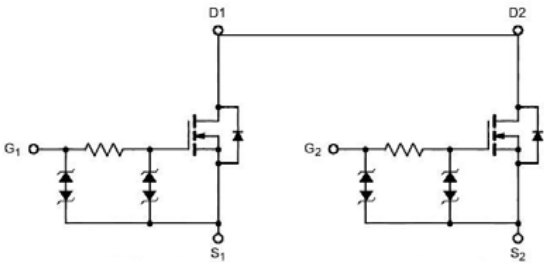
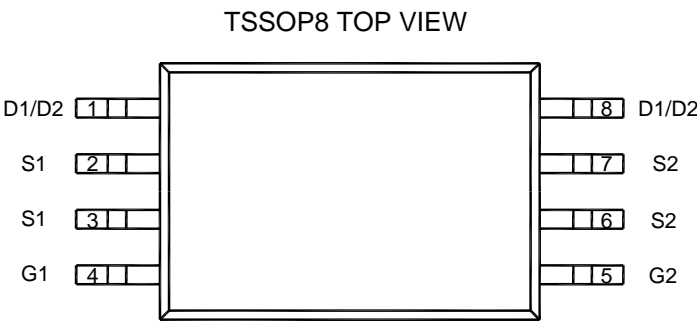
**Features**

- High density cell trench design for low  $R_{ds(on)}$
- Surface mount package
- RoHS and Halogen-Free compliant

**Applications**

- Li-ion battery management applications

### Pin Configuration



### Packing Information

Device	Marking	Reel Size	Tape Width	Quantity
ECG8205A	82A .XXX	13'	12mm	3000pcs

### Absolute Maximum Ratings (at $T_A=25^{\circ}C$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Units
$V_{DS}$	Drain-Source Voltage		20	V
$V_{GS}$	Gate-Source Voltage		±10	V
$I_D$	Continuous Drain Current at $V_{GS}=10V$	$T_C=25^{\circ}C$	5	A
		$T_C=70^{\circ}C$	4.1	A
$I_{DM}$	Pulse Drain Current Tested		20	A
$P_D$	Power Dissipation	$T_C=25^{\circ}C$	1.25	W
$T_J, T_{STG}$	Junction and Storage Temperature Range		-55 to 150	$^{\circ}C$

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient	69	$^{\circ}C/W$

## Electrical Characteristics (at $T_J = 25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V,I <sub>D</sub> =250uA	20	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =16V,V <sub>GS</sub> =0V	--	--	1	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> =0V,V <sub>GS</sub> =±12V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA	0.45	0.6	0.8	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V,I <sub>D</sub> =4A	--	19	22	mΩ
		V <sub>GS</sub> =2.5V,I <sub>D</sub> =3A	--	25	30	mΩ
V <sub>SD</sub>	Forward Voltage	I <sub>SD</sub> =1.7A,V <sub>GS</sub> =0V	--	0.7	1.3	V
Dynamic Parameters						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V,V <sub>DS</sub> =10V f=1MHZ	--	595	--	pF
C <sub>oss</sub>	Output Capacitance		--	90	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	71	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =10V,I <sub>D</sub> =5A V <sub>GS</sub> =4.5V	--	12	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	2.1	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	3.3	--	nC
Switching Parameters						
t <sub>D(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =10V,I <sub>D</sub> =5A R <sub>G</sub> =6Ω,V <sub>GS</sub> =4.5V	--	23	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	30	--	nS
t <sub>D(off)</sub>	Turn-off Delay Time		--	56	--	nS
t <sub>f</sub>	Turn-off Fall Time		--	21	--	nS
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =5A di/dt=100A/us	--	14	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		--	5	--	nC

Typical Characteristics

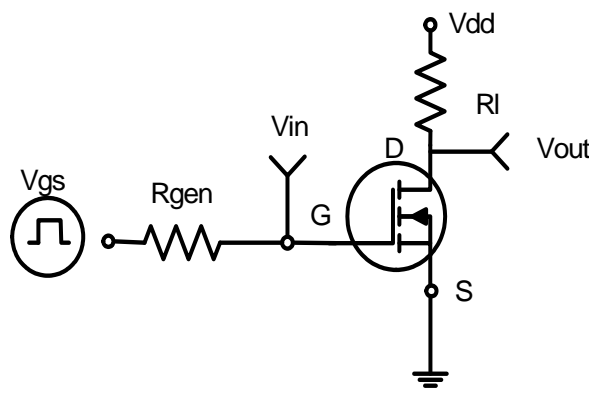


Figure 1: Switching Test Circuit

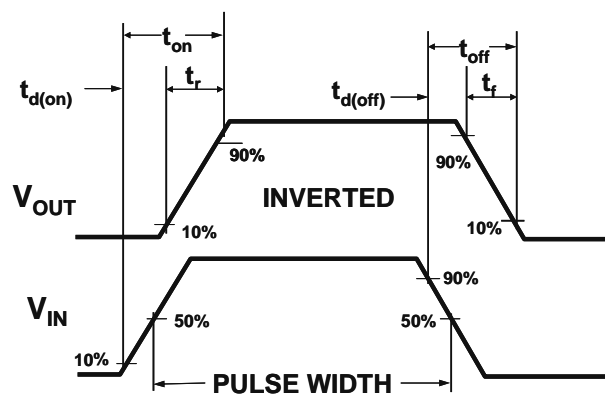


Figure 2: Switching Waveforms

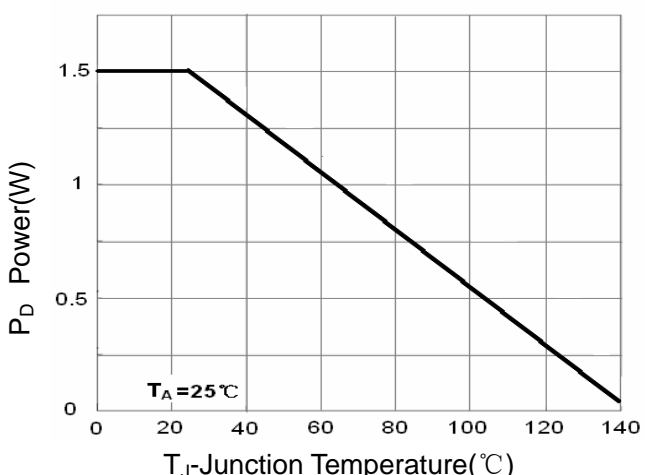


Figure 3 Power Dissipation

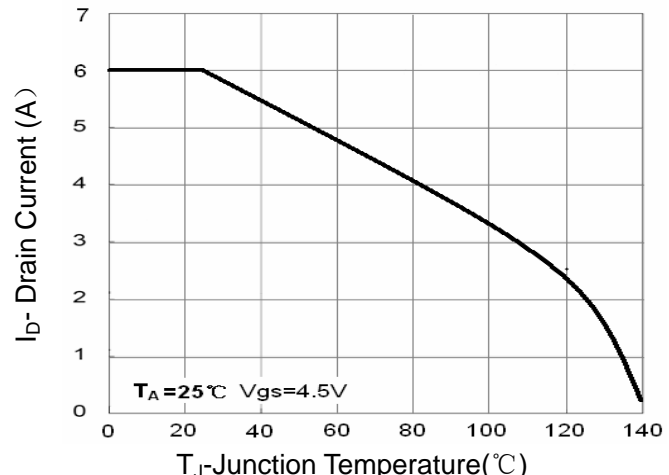


Figure 4 Drain Current

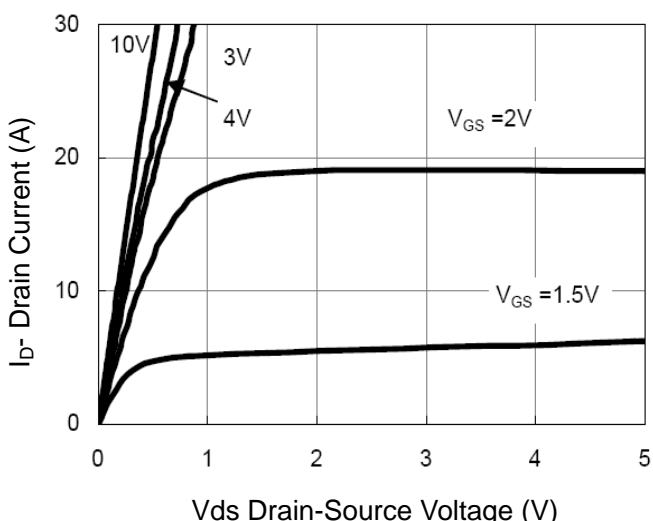


Figure 5 Output CHARACTERISTICS

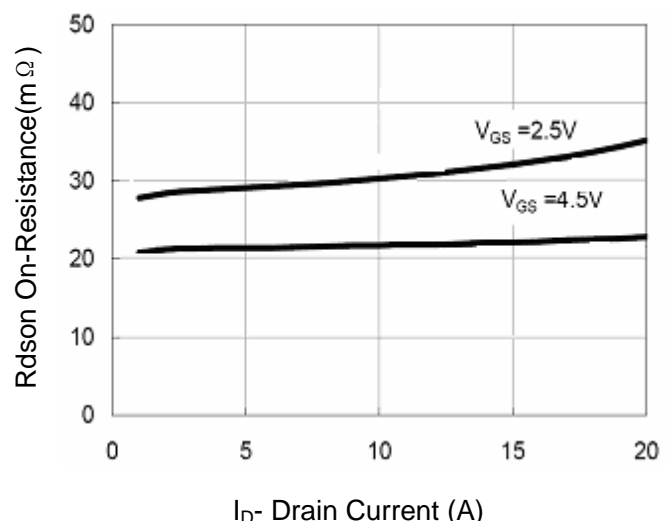


Figure 6 Drain-Source On-Resistance

Typical Characteristics

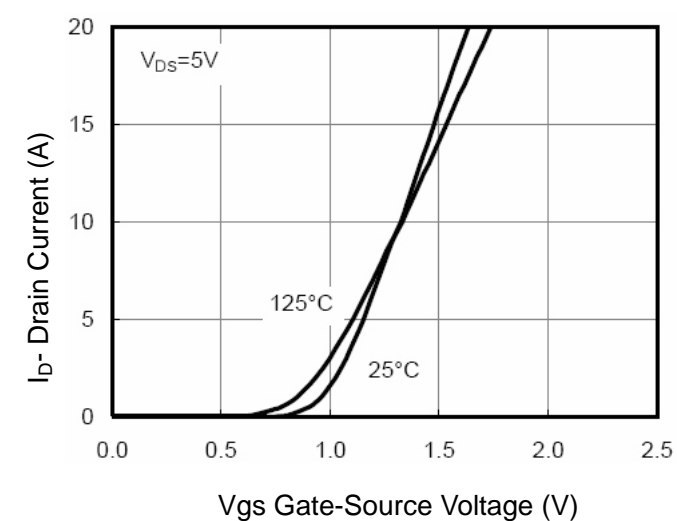


Figure 7 Transfer Characteristics

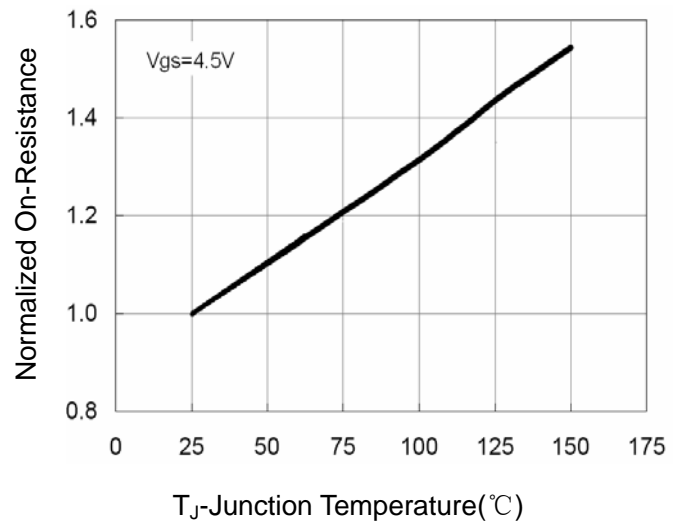


Figure 8 Drain-Source On-Resistance

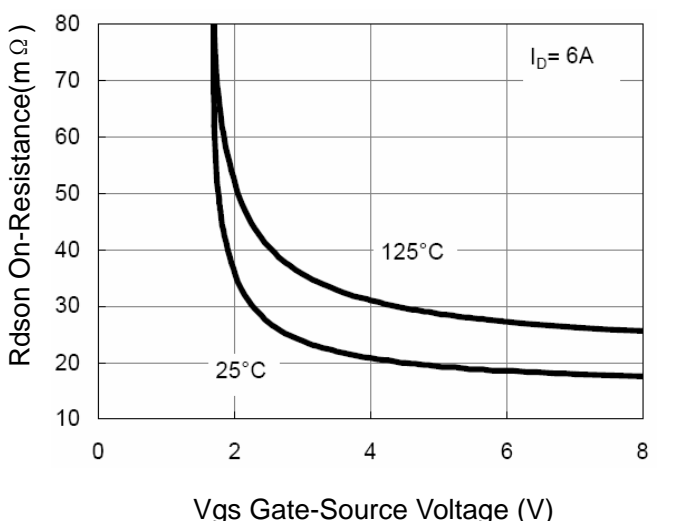


Figure 9 Rdson vs Vgs

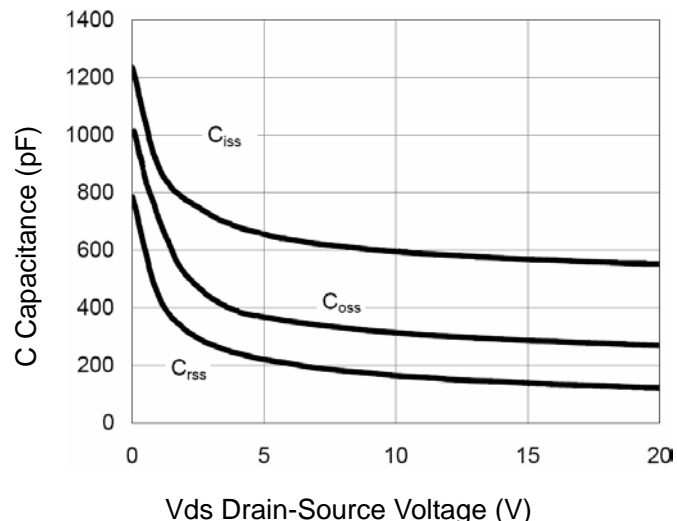


Figure 10 Capacitance vs Vds

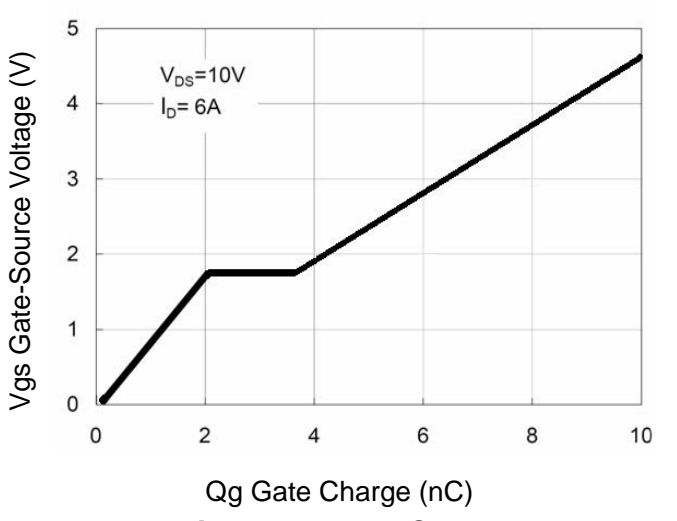


Figure 11 Gate Charge

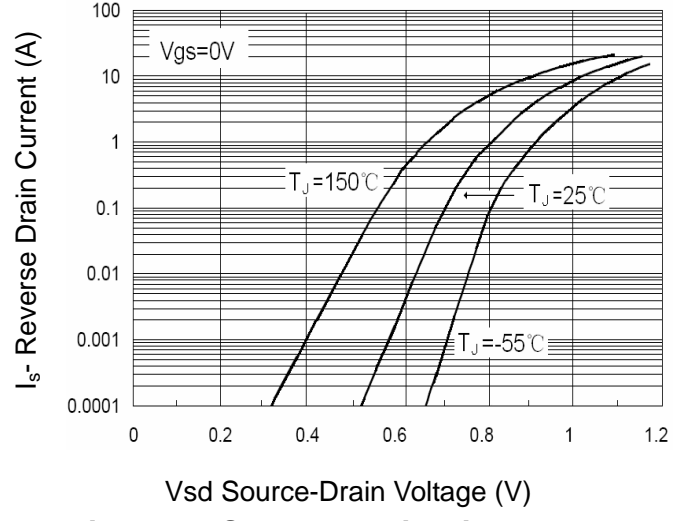
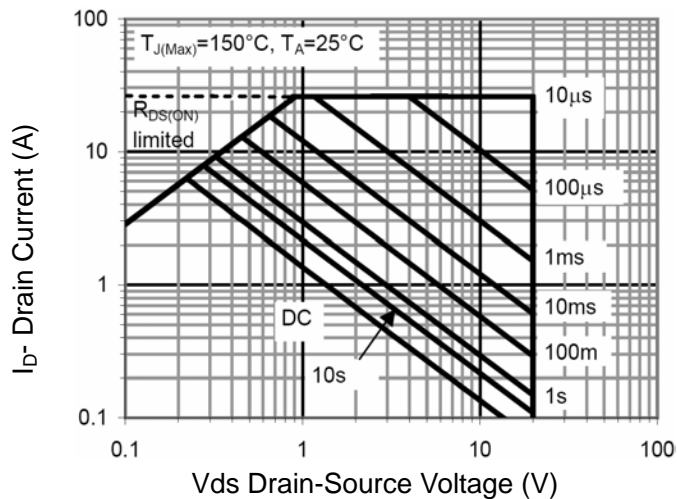
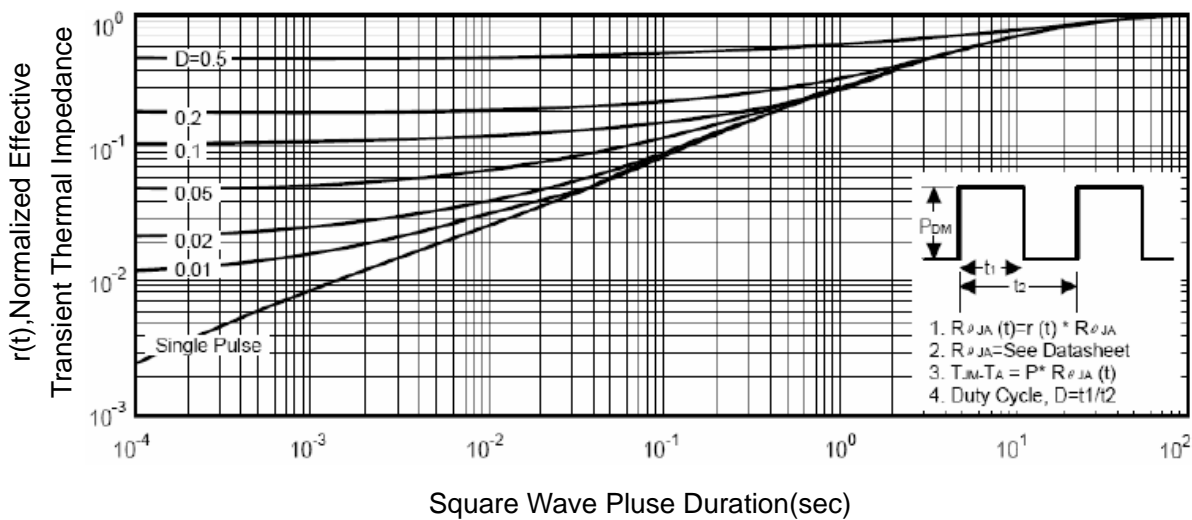


Figure 12 Source- Drain Diode Forward

Typical Characteristics

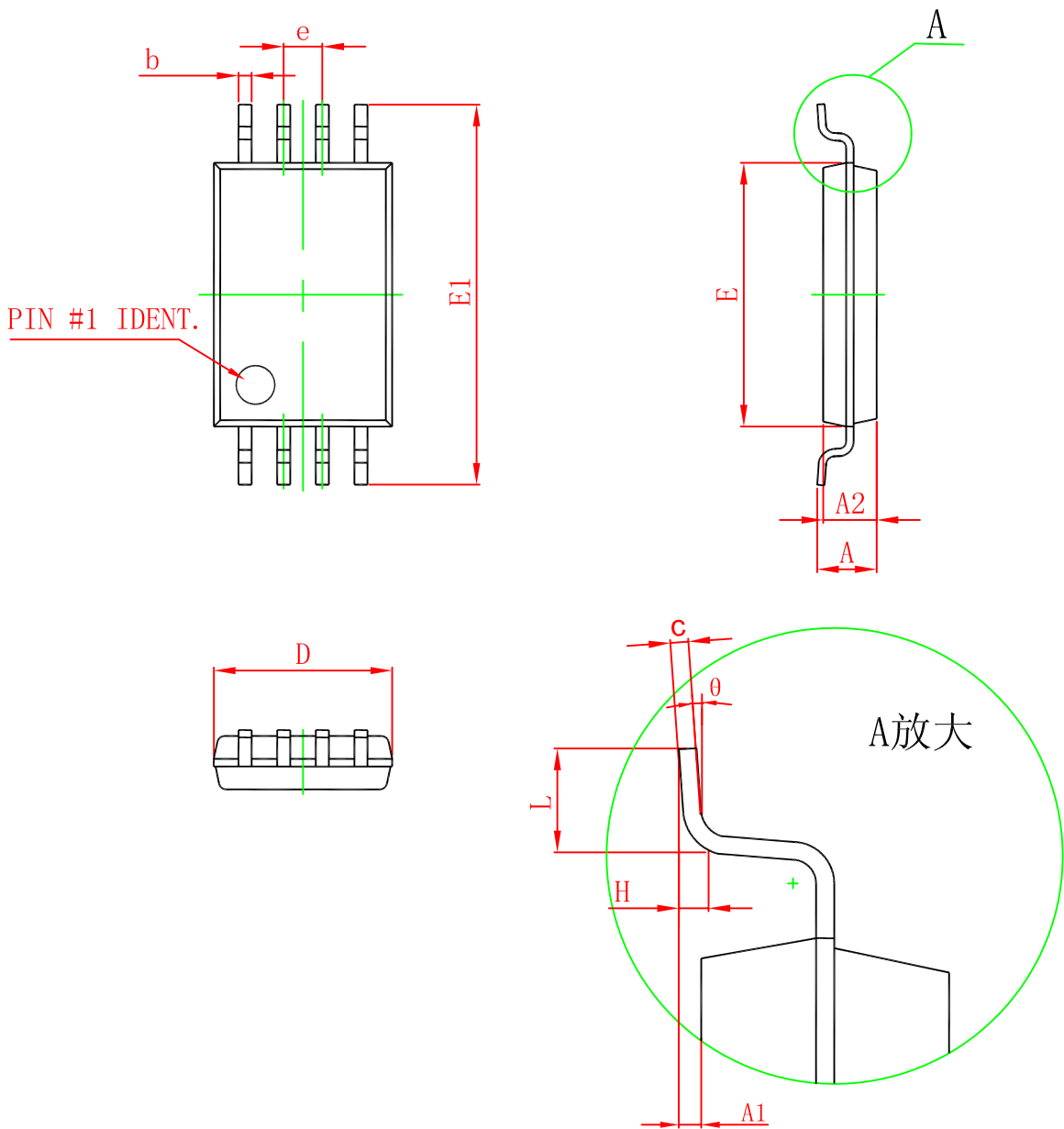


**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**

TSSOP8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
D	2.900	3.100	0.114	0.122
E	4.300	4.500	0.169	0.177
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
E1	6.250	6.550	0.246	0.258
A		1.100		0.043
A2	0.800	1.000	0.031	0.039
A1	0.020	0.150	0.001	0.006
e	0.65 (BSC)		0.026 (BSC)	
L	0.500	0.700	0.020	0.028
H	0.25 (TYP)		0.01 (TYP)	
$\theta$	1°	7°	1°	7°